



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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(0.80 mm) .0315"

BTE, BSE SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μm (1.27 μm) Ni
Current Rating: 2 A per pin (1 pin powered per row)
Operating Temp Range: -55 °C to +125 °C
Voltage Rating: 225 VAC with 5 mm Stack Height
Max Cycles: 100
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (020-080) (0.15 mm) .006" max (100-120)
Board Stacking: For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197
-02	(8.00) .315

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30 μm (0.76 μm) Gold
- Edge Mount Capability
- Friction Lock option
- 11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)

Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE — **NO. OF POSITIONS PER ROW** — **LEAD STYLE** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BSE**

-020, -040, -060, -080, -100, -120

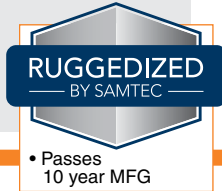
Specify LEAD STYLE from chart

LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

-F = Gold Flash on contact, Matte Tin on tail
-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail
-C* = Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad
-TR = Tape & Reel (60 positions maximum)

***Note:** -C Plating passes 10 year MFG testing



BSE — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BTE**

-020, -040, -060, -080, -100, -120

-F = Gold Flash on contact, Matte Tin on tail
-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail
-C* = Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

-TR = Tape & Reel (80 positions maximum)

***Note:** -C Plating passes 10 year MFG testing